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Contract

## Silicon Wafers for Test Chips

THE OPEN UNIVERSITY

UK7: Contract details notice - Procurement Act 2023 - [view information about notice types](#)

Notice identifier: 2025/S 000-049225

Procurement identifier (OCID): ocds-h6vhtk-055960 ([view related notices](#))

Published 15 August 2025, 3:27pm

### Scope

### Reference

OUPA11504

### Description

As part of the existing Technology Development Element (TDE) contract with the European Space Agency (ESA), the Open University (OU), in company with Teledyne-e2v, are required to procure and test three experimental test chips for characterisation and testing.

Phase 1: To procure Silicon wafers for the manufacture of Front Side Illuminated (FSI) soft X-ray Complementary Metal Oxide Semiconductor (CMOS) imaging detectors to characterise their Electro Optical (EO) performance both pre and post irradiation.

Phase 2: A potential second phase subject to funding to process any remaining Silicon wafers from the first phase for the manufacture of Back Side Illuminated (BSI) soft X-ray CMOS imaging detectors to characterise their EO performance both pre and post irradiation.

Phase 3: A potential third phase subject to funding to procure Silicon wafers to manufacture another batch of either FSI or BSI soft X-ray CMOS imaging detectors for further characterisation of their EO performance both pre and post irradiation.

Cost

Phase 1: £220,000

Phase 2: £250,000

Phase 3: £350,00

Total: £820,000

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## **Contract 1. Silicon Wafers for Test Chips**

### **Supplier**

- X-FAB Sarawak Sdn. Bhd.

### **Contract value**

- 220000 EUR excluding VAT
- 220000 EUR including VAT

Above the relevant threshold

### **Date signed**

17 July 2025

### **Contract dates**

- 18 July 2025 to 31 January 2026
- Possible extension to 1 October 2029
- 4 years, 2 months, 15 days

Description of possible extension:

Extension End Date:

Phase 2: March 2028

Phase 3: September 2029

### **Main procurement category**

Goods

### **CPV classifications**

- 38000000 - Laboratory, optical and precision equipments (excl. glasses)

### **Contract locations**

- UKC - North East (England)
- UKD - North West (England)
- UKE - Yorkshire and the Humber
- UKF - East Midlands (England)

- UKG - West Midlands (England)
- UKH - East of England
- UKI - London
- UKJ - South East (England)
- UKK - South West (England)

### **Justification for not setting key performance indicators**

Not applicable.

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### **Other information**

#### **Conflicts assessment prepared/revised**

Yes

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### **Procedure**

#### **Procedure type**

Direct award

#### **Direct award justification**

Single supplier - technical reasons

The following conditions are met in relation to the public contract-

- a) due to an absence of competition for technical reasons, only a particular supplier can supply the goods, services or works required, and
- b) there are no reasonable alternatives to those goods, services or works.

Teledyne-e2v have previously performed a competitor analysis and based on a comparison of price and technical performance, XFAB were selected as the preferred supplier for all their silicon chip products. As a result, Teledyne's CMOS imaging device design and manufacturing plans for this project have been developed to align with XFAB's design rules and processes. Consequently, in order to meet the requirements of the ESA agreement the OU must procure wafers from XFAB to ensure compatibility with Teledyne's design and manufacturing standards.

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## Supplier

### **X-FAB Sarawak Sdn. Bhd.**

- Public Procurement Organisation Number: PLGZ-1483-CXTX

1 Silicon Drive, Sama Jaya Free Industrial Zone

Kuching · Sarawak

93350

Malaysia

Email: [KCH-Customer-Service-Group@xfab.com](mailto:KCH-Customer-Service-Group@xfab.com)

Website: <http://www.xfab.com>

Small or medium-sized enterprise (SME): No

Voluntary, community or social enterprise (VCSE): No

Supported employment provider: No

Public service mutual: No

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## **Contracting authority**

### **THE OPEN UNIVERSITY**

- Charity Commission (England and Wales): RC000391
- Public Procurement Organisation Number: PYNW-6296-ZJQQ

Walton Hall

Milton Keynes

MK7 6AA

United Kingdom

Email: [finance-tenders@open.ac.uk](mailto:finance-tenders@open.ac.uk)

Region: UKJ12 - Milton Keynes

Organisation type: Public authority - sub-central government